

0.28 Inch One Digit Display SMD
OSK1028A-IX (Common Anode type)
OSK1028A-LX (Common Cathode type)

■ **Features**

- 0.28 Inch One Digit Display
- Long lifetime operation
- IC compatible
- Low power dissipation
- Gray surface & white segment or dot
- RoHS compliant

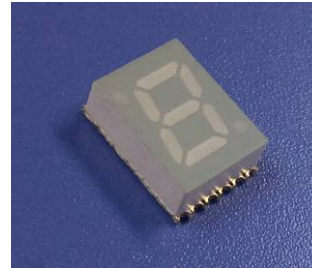
■ **Applications**

- Counting device
- Clock

■ **Absolute Maximum Rating (Ta=25°C)**

Item	Symbol	Value		Unit
		B/TG	YG/Y/O/R/RA	
DC Forward Current	I _F	25	25	mA
Pulse Forward Current#	I _{FP}	80	80	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _t	90	65	mW
Operating Temperature	T _{opr}	-30~ +85		°C
Storage Temperature	T _{stg}	-40~ +100		°C
Lead Soldering Temperature(1.6mm Below body)	T _{sol}	260°C/3sec		°C

■ **Photo**



#Pulse width Max.10ms Duty ratio max 1/10

#Reflow time Max.3seconds

■ **Electrical -Optical Characteristics (Ta=25°C)**

Part Number	Color		V _F (V)			I _R (μA)	I _v (mcd)			λD(nm)			
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
			I _F =20mA			V _R =5V	I _F =10mA			I _F =20mA			
OSK1028A-IB(LB)	Blue	B	■	-	3.1	3.6	100	3	9	15	465	470	475
OSK1028A-IG(LG)	True Green	TG	■	-	3.1	3.6	100	5	10	15	510	520	530
OSK1028A-IYG(LYG)	Yellow Green	YG	■	-	2.1	2.6	100	2	6	10	565	570	575
OSK1028A-IY(LY)	Yellow	Y	■	-	2.1	2.6	100	2	6	10	585	590	595
OSK1028A-IO(LO)	Orange	O	■	-	2.1	2.6	100	2	6	10	600	605	610
OSK1028A-IR(LR)	Red	R	■	-	2.1	2.6	100	2	6	10	625	630	640

*1 Tolerance of measurements of dominant wavelength is±1nm

*2 Tolerance of measurements of luminous intensity is±15%

*3 Tolerance of measurements of forward voltage is±0.1V

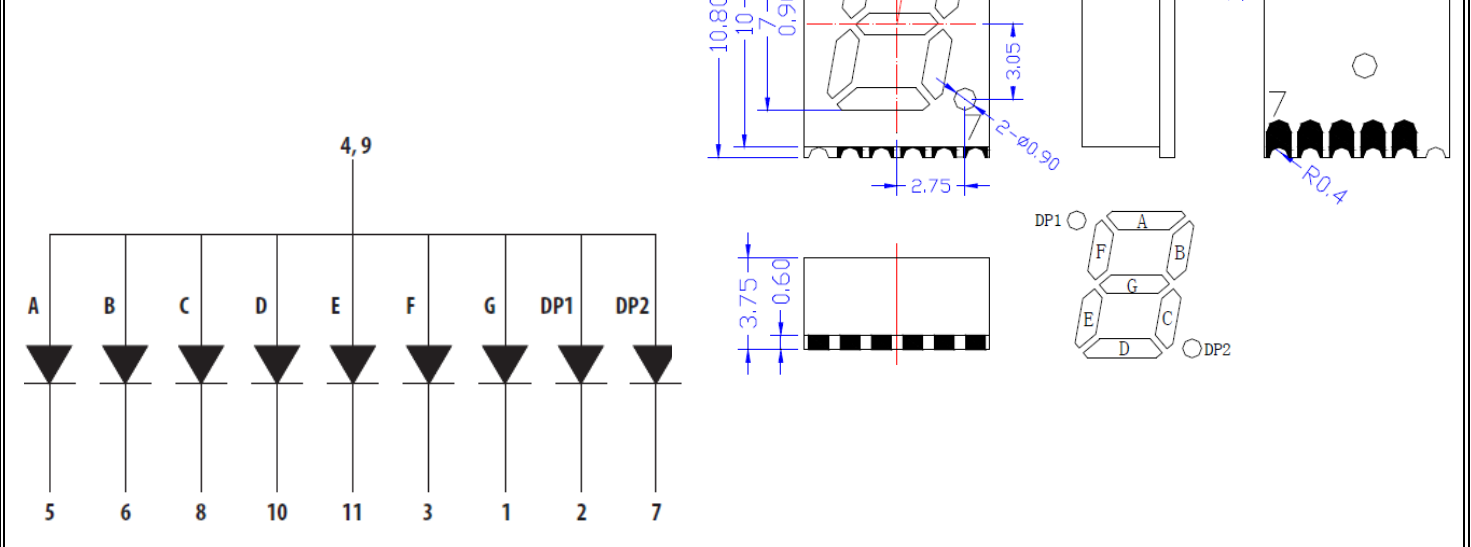
■ Package Dimensions

OSK1028A-IX

(Common Anode type)

Note:

1, Unit : mm (Tolerance: ±0.25mm unless otherwise noted)

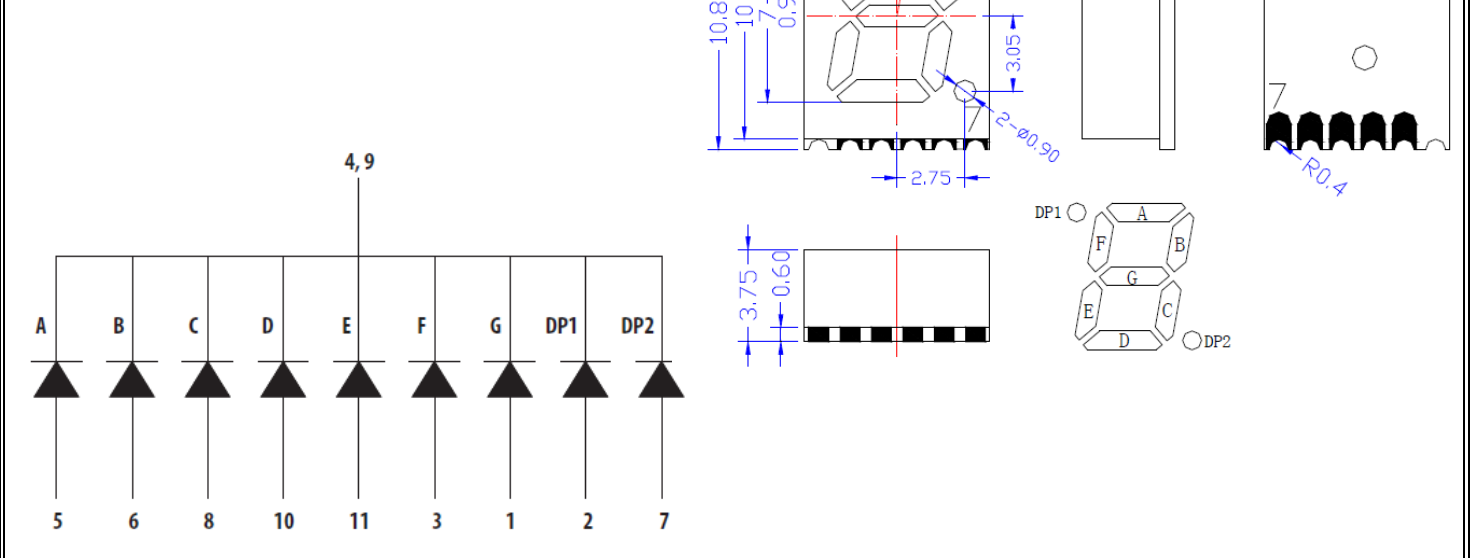


OSK1028A-LX

(Common Cathode type)

Note:

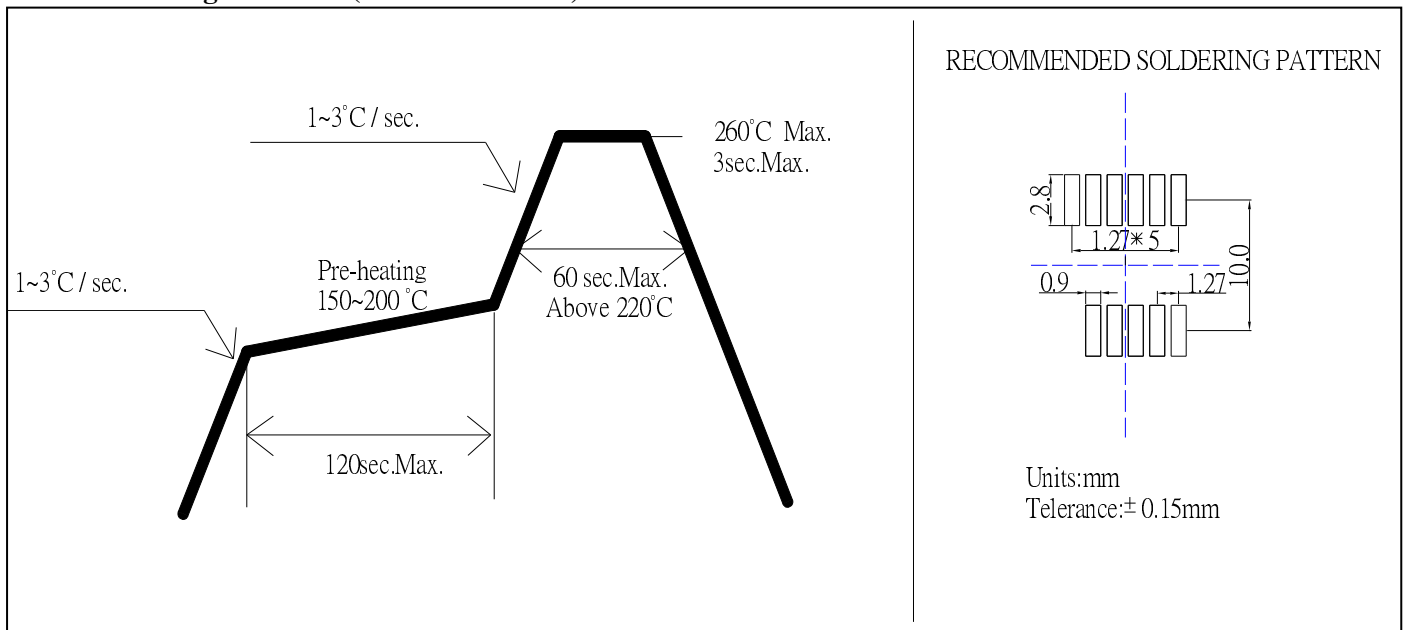
1, Unit : mm (Tolerance: ±0.25mm unless otherwise noted)



■ Soldering Conditions

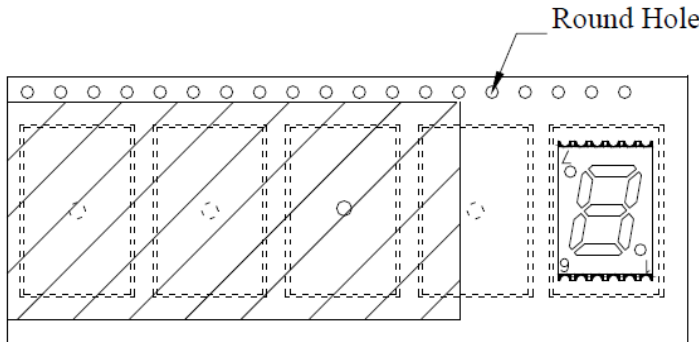
Reflow Soldering		Hand Soldering		
Pre-Heat	150 ~ 200°C	Temperature Soldering time	350°C Max. 3 sec. Max. (one time only)	
Pre-Heat Time	120 sec. Max.			
Peak temperature	260°C Max.			
Dipping Time	3 sec. Max.			
Condition	Refer to Temperature-profile			

• Reflow Soldering Condition(Lead-free Solder)

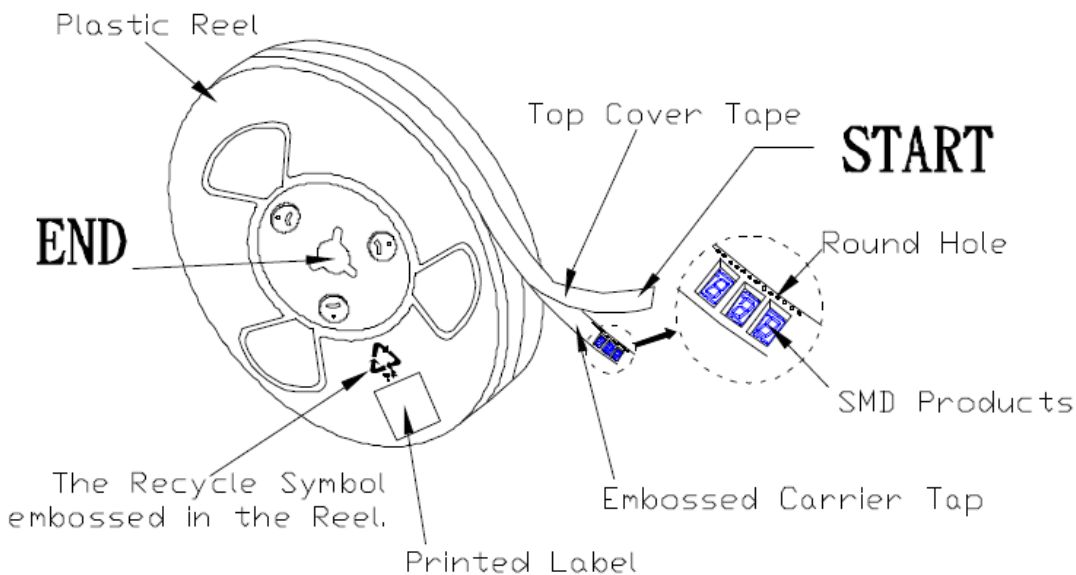


- *Recommended soldering conditions vary according to the type of LED
- *Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- *A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

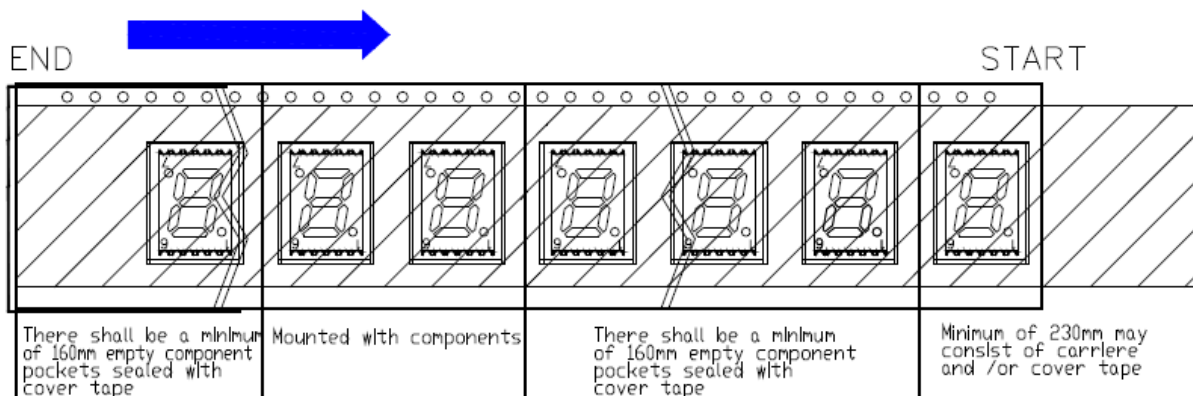
■ **The Products In The Reel Of Direction**



■ **Label Direction & Content In The Roll**



■ **USER FEED DIRECTION**



■ **Package Criteria:**

1. Total unit per reel is 1000PCS.
2. Max 5 reels/5000PCS are packaged in each cartton



CAUTION

This bag contains

MOISTURE-SENSITIVE DEVICES

LEVEL

3

1. Calculated shelf life in sealed bag: 12 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH).
2. Peak package body temperature: Per Product Label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
 - a) Mounted within: 168 hours of factory conditions $\leq 30^{\circ}\text{C}/60\% \text{RH}$
 - b) stored per J-STD-033
4. Devices require bake, before mounting, if:
 - a) Humidity Indicator Card is $>10\%$ when read at $23 \pm 5^{\circ}\text{C}$
 - b) 3a or 3b not met.
5. If baking is required, devices may be baked for 20 hours at $60 \pm 5^{\circ}\text{C}$

Bag Seal Date: _____

If Blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020